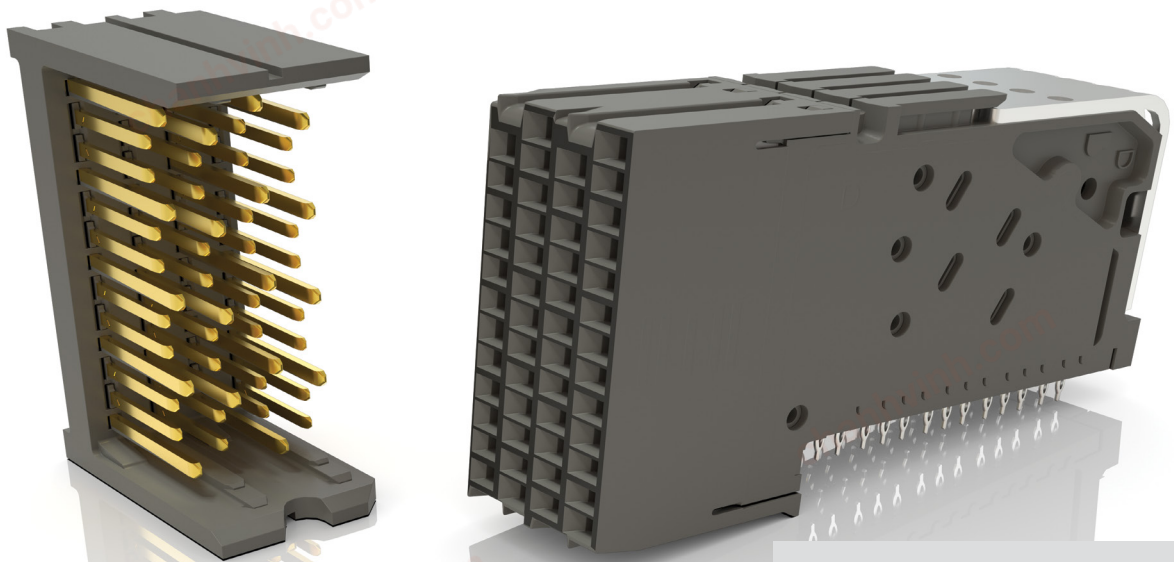
chanhvinh.com

XCede® HD

HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH

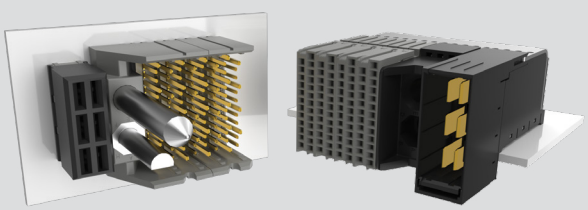
16 Gbps



FEATURES & BENEFITS

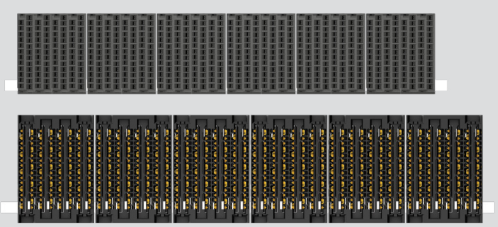
- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and side walls available
- 85 Ω and 100 Ω options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane. Visit **samtec.com?BSP** or contact **HSBP@samtec.com**
- Press-fit extraction and insertion tool options; please visit **samtec.com/tooling** for details

MODULAR DESIGN



Signal, Power & Keying / Guidance options can be customized in any configuration

HIGH-DENSITY, SMALL FORM FACTOR



XCede® HD
Up to 84 pairs per linear inch

Traditional Backplane
Up to 76 pairs per linear inch

(Both shown with six 4-pair, 8 column receptacles)

KEY SPECIFICATIONS

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING
HDTM/HDTF	LCP	Phosphor Bronze (HDTM) Copper Alloy (HDTF)	Au or Sn over 50 µ" (1.27 µm) Ni	-40 °C to + 105 °C	1.5 A per contact	48 VAC/ /68 VDC
HPTS/HPTT	LCP	Copper Alloy	Au or Sn over 50 µ" (1.27 µm) Ni	-40 °C to + 105 °C	10 A per blade	48 VAC/ /68 VDC

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.

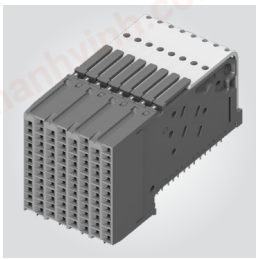
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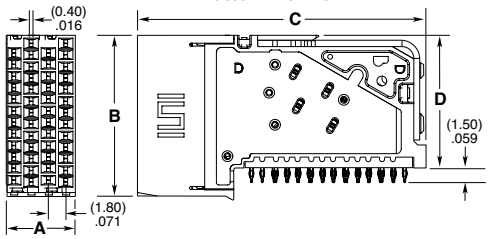
XCede® HD

(1.80 mm) .071" PITCH • HIGH-DENSITY BACKPLANE RECEPTACLE

HDTF	PAIRS PER COLUMN	NO. OF COLUMNS	PLATING	RA	WAFERS	IMPEDANCE
	–3, –4, –6	–04, –06, –08	–S = 30 µ" (0.76 µm) Gold on Contact Area, Matte Tin on Tail		–LC = Standard –HS = High-Speed	–100 = 100 Ω –085 = 85 Ω

HDTF
Board Mates:
HDTM





NO. OF COLUMNS	A
–04	(7.2) .283
–06	(10.8) .425
–08	(14.4) .567

PAIRS PER COLUMN	B	C	D
–3	(12.8) .504	(26.0) 1.02	(9.9) .390
–4	(16.4) .646	(29.4) 1.16	(13.5) .531
–6	(23.6) .929	(36.6) 1.44	(20.7) .815

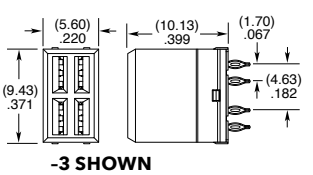
View complete specifications at: samtec.com?HDTF

(3.20 mm) .126" PITCH • POWER MODULES

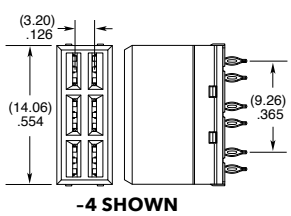
HPTS	BODY HEIGHT	PLATING	D	ORIENTATION
= Socket	Based on Pair Count of Signal Modules (HDTM) –3, –4, –6	–S = Standard Gold on Contact Area, Matte Tin on Tail		–VT = Vertical

HPTS
Mates with:
HPTT, BSP

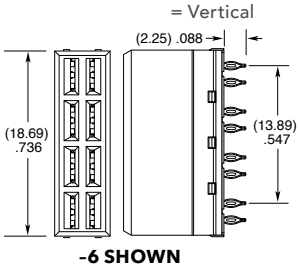




-3 SHOWN



-4 SHOWN



-6 SHOWN

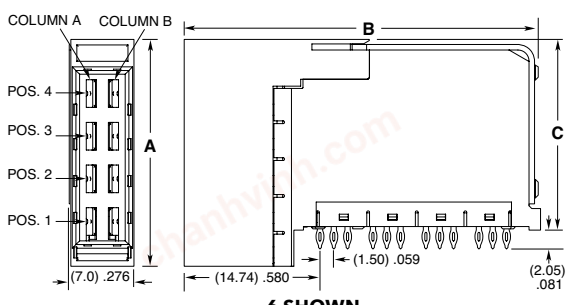
View complete specifications at: samtec.com?HPTS

HPTT	BODY HEIGHT	PLATING	POSITION NO. 1	POSITION NO. 2	POSITION NO. 3	POSITION NO. 4	D	ORIENTATION
= Terminal	Based on Pair Count of Signal Modules (HDTF, BSP) –3, –4, –6	–S = Standard Gold on Contact Area, Matte Tin on Tail	Contact Wipe Column A & B –3 = (4.5 mm) 0.18" –6 = (5.5 mm) 0.22"	Contact Wipe Column A & B –3 = (4.5 mm) 0.18" –6 = (5.5 mm) 0.22"	Contact Wipe Column A & B (–4 & –6 Height Only) –3 = (4.5 mm) 0.18" –6 = (5.5 mm) 0.22"	Contact Wipe Column A & B (–6 Height Only) –3 = (4.5 mm) 0.18" –6 = (5.5 mm) 0.22"		–RA = Right-angle

HPTT
Mates With:
HPTS



BODY HEIGHT	A	B	C
–3	(13.8) .543	(28.1) 1.11	(9.80) .386
–4	(17.4) .685	(31.2) 1.23	(13.50) .531
–6	(24.6) .969	(38.7) 1.52	(20.70) .815



-6 SHOWN

View complete specifications at: samtec.com?HPTT

Notes:
Some lengths, styles and options are non-standard, non-returnable. XCede® is a registered trademark of Amphenol.

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